

VERSION

No.	Version	Date	Details	Name	Check
1	V1.0.0	2020/7/20	Initial	wangcheng	
2	V1.0.1				

PCB Process Description	
Board Thickness	1.0mm
Base material	Copper-clad laminate
Copper Thickness	1 oz
Pad Processing	HAL&SMOBC
Solder/Mask	

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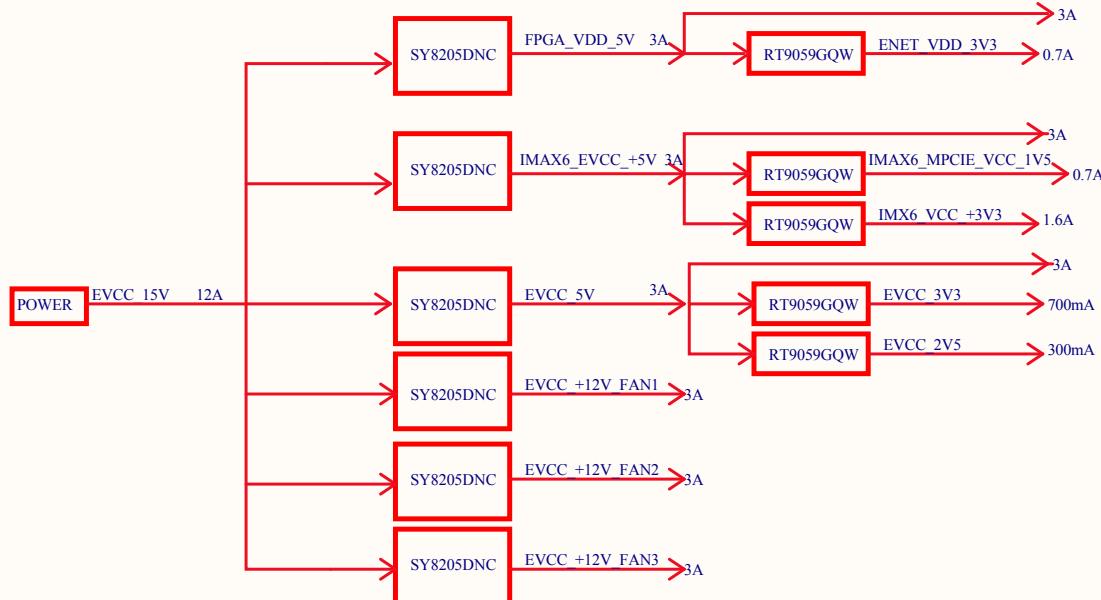
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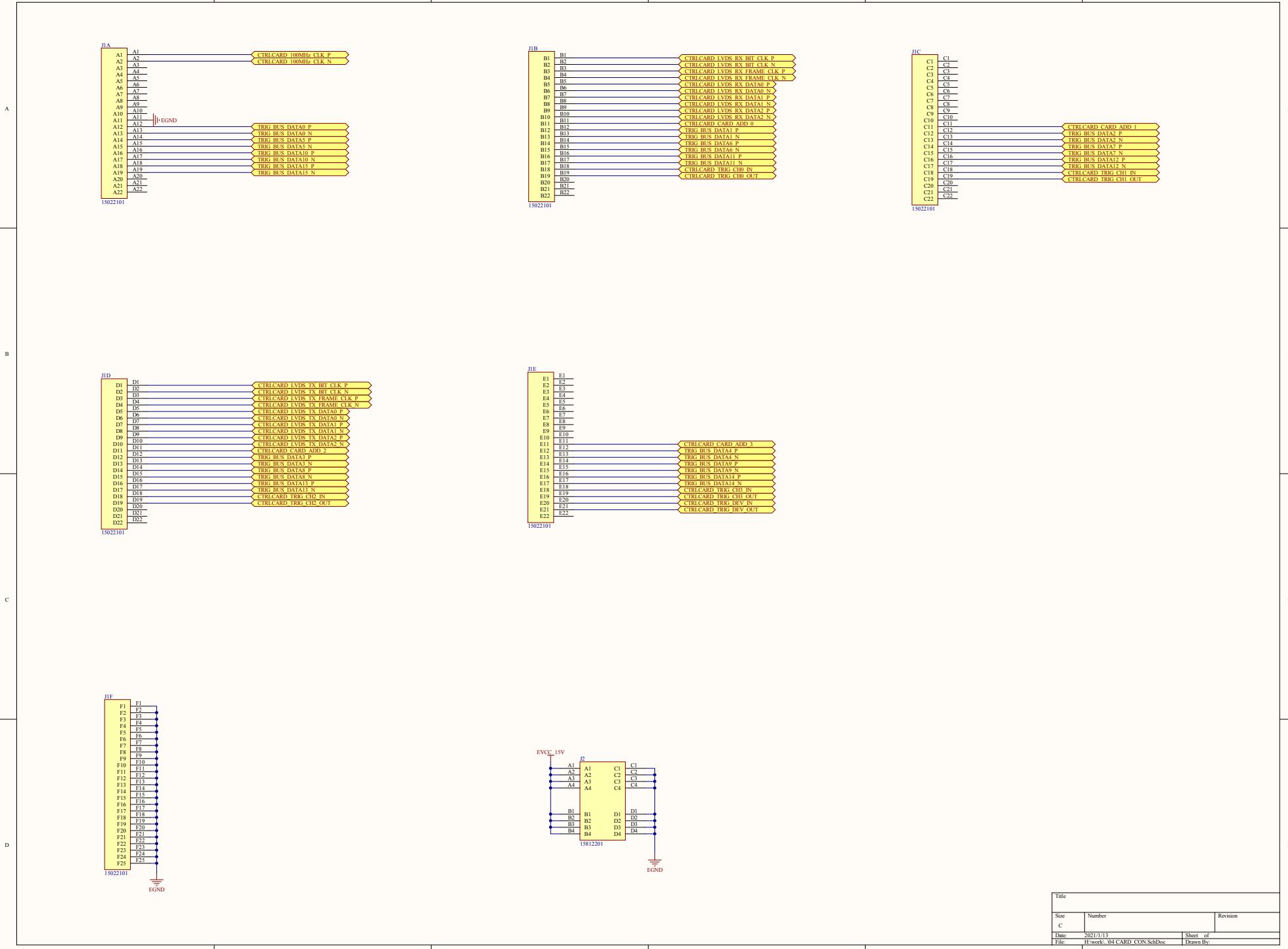
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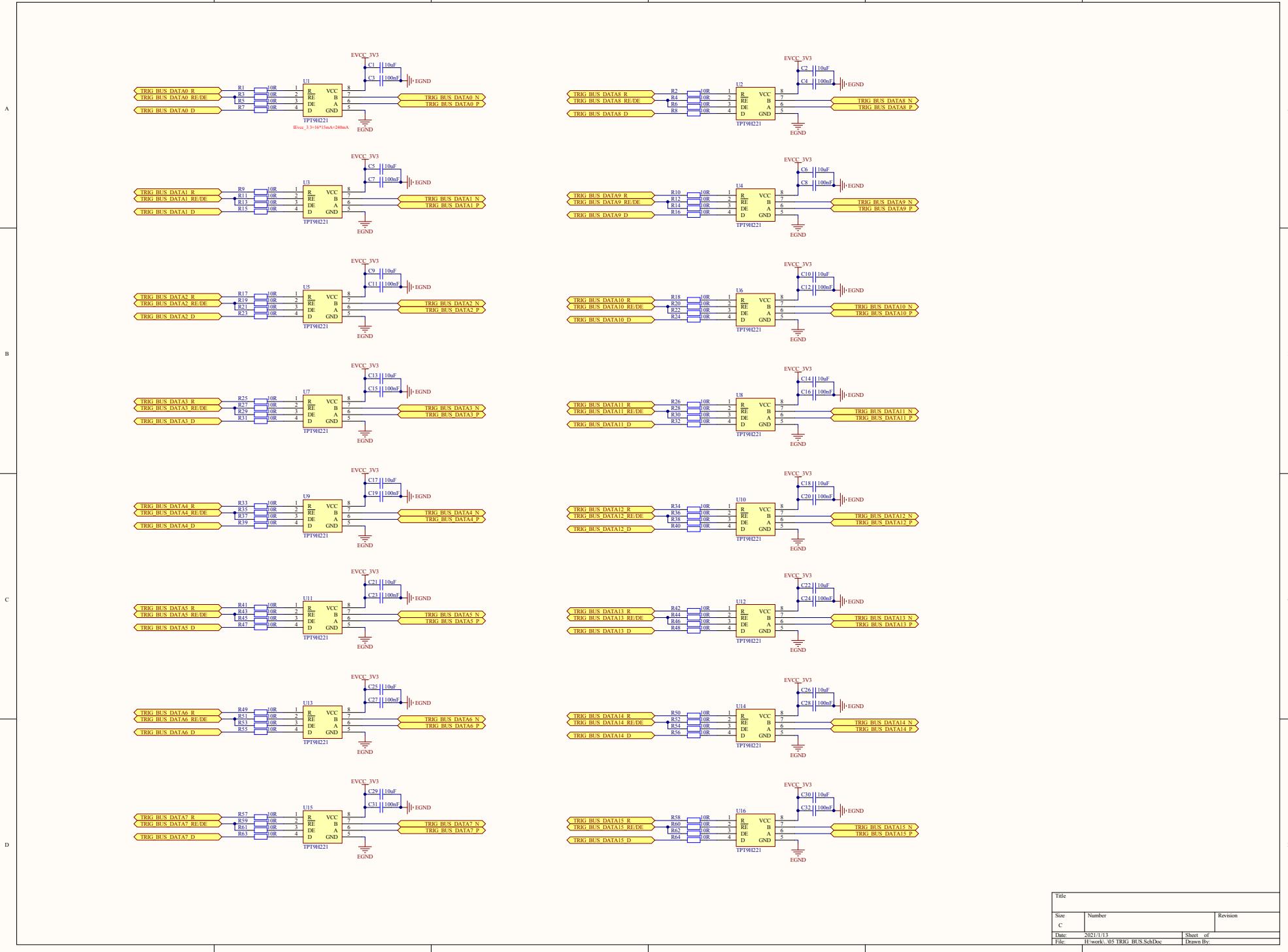
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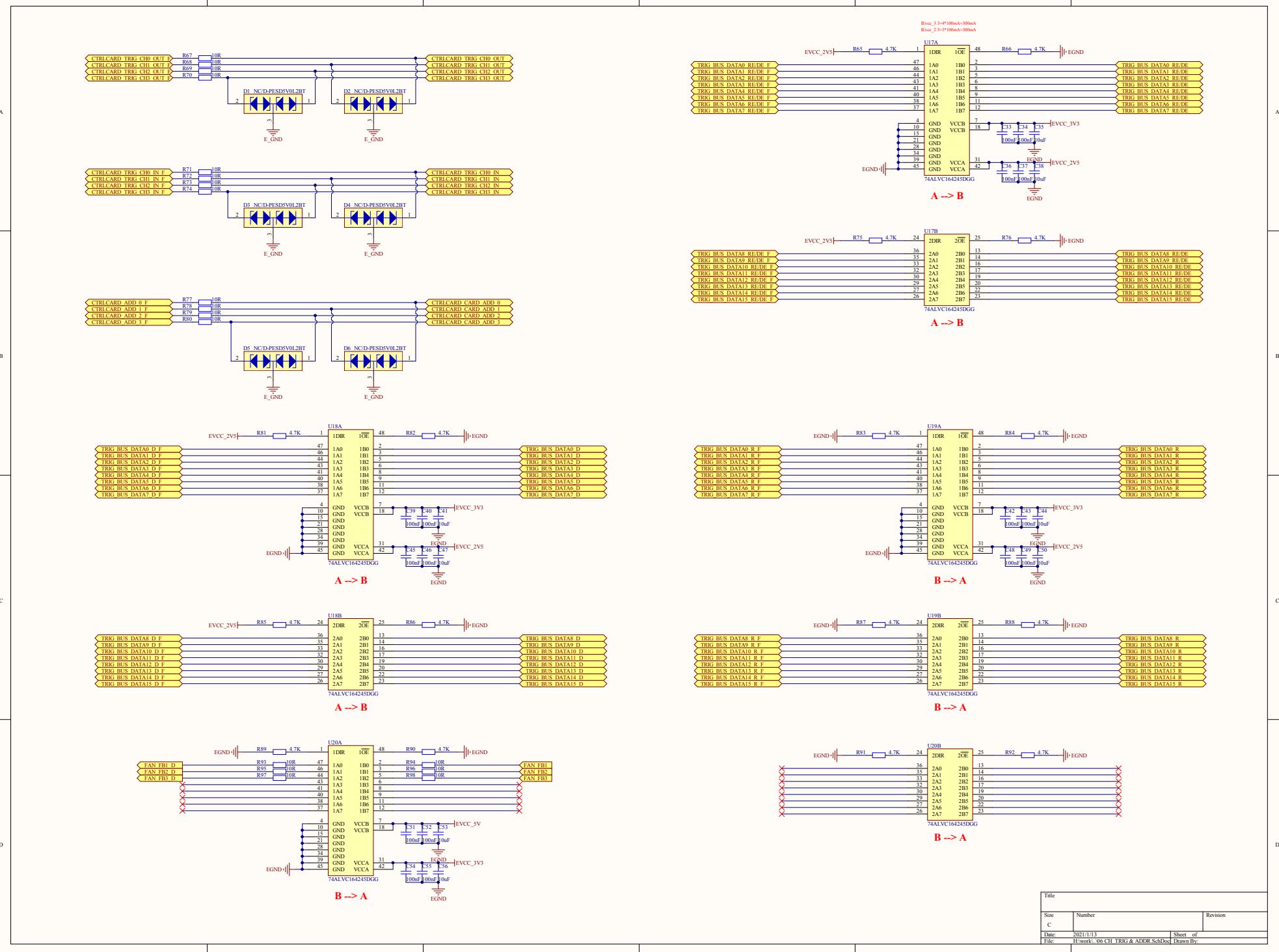
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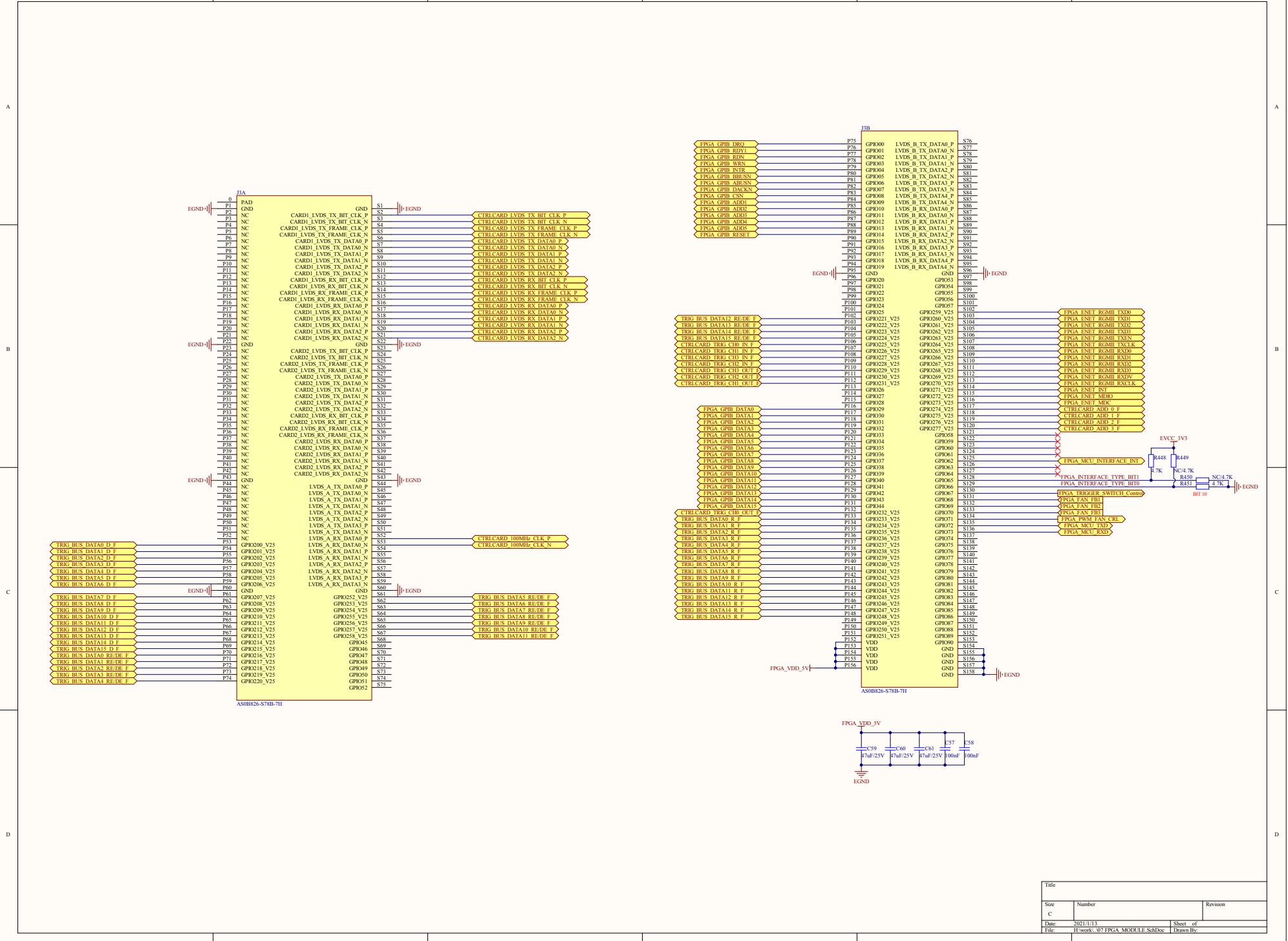


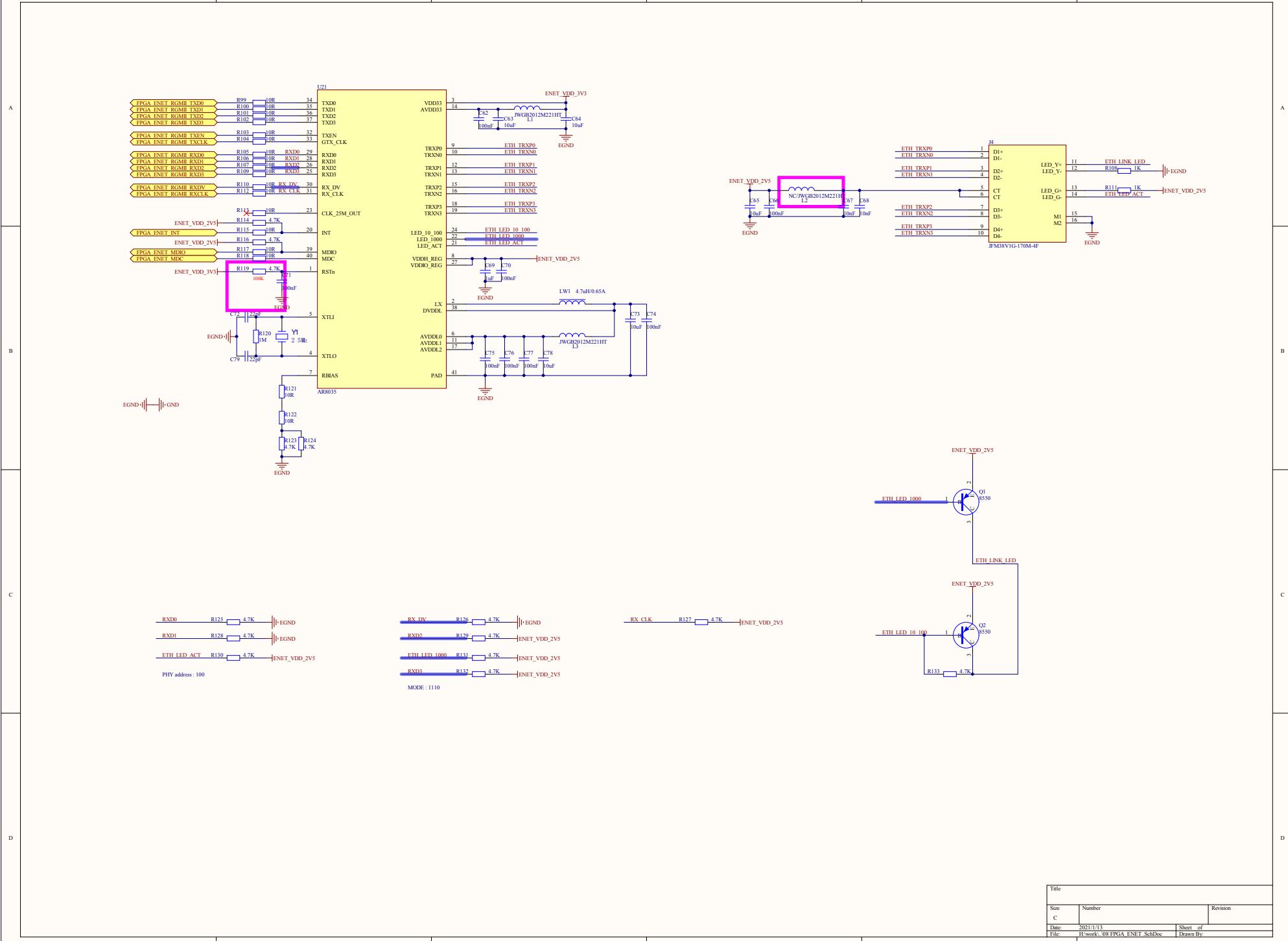
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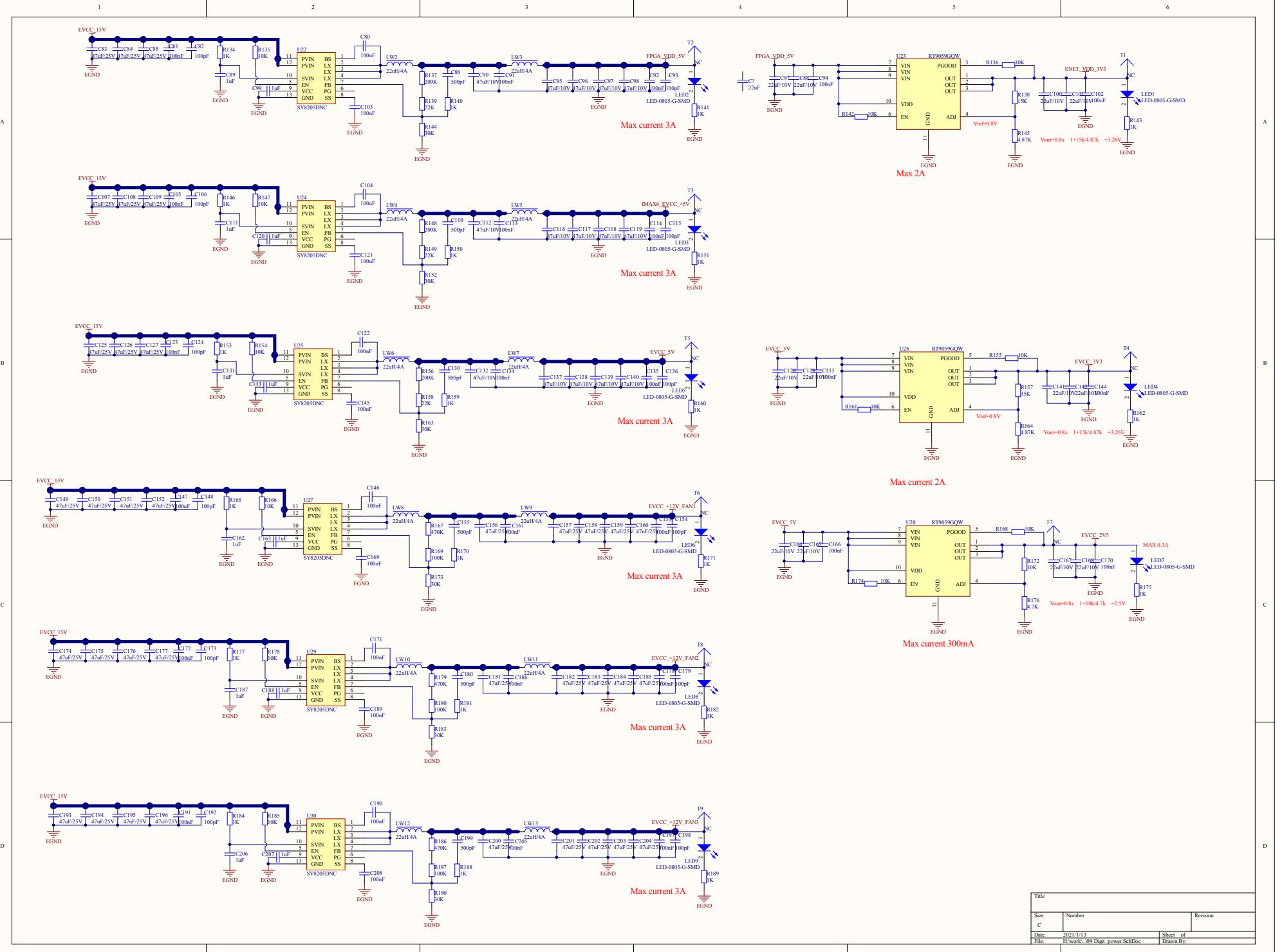


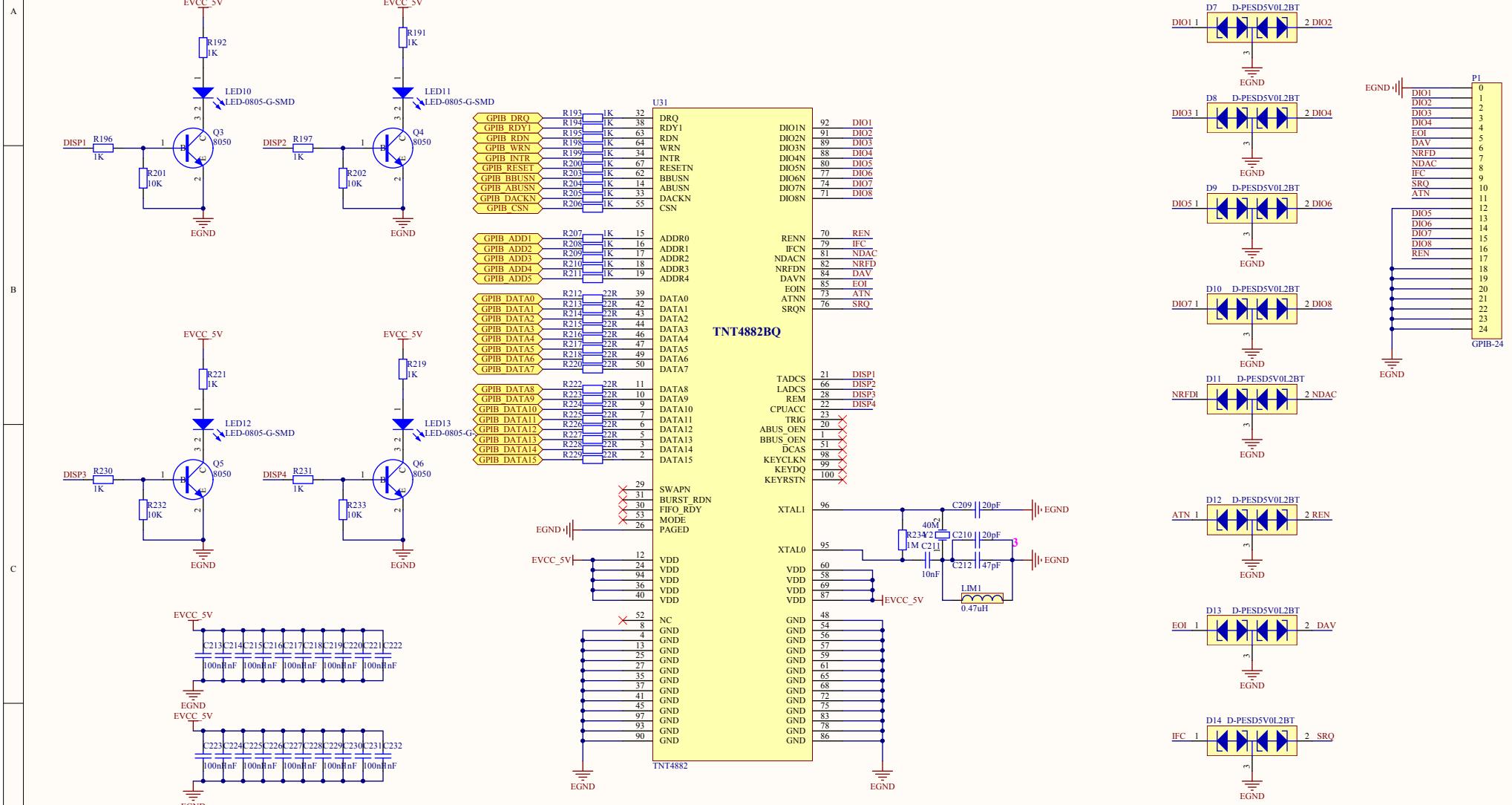




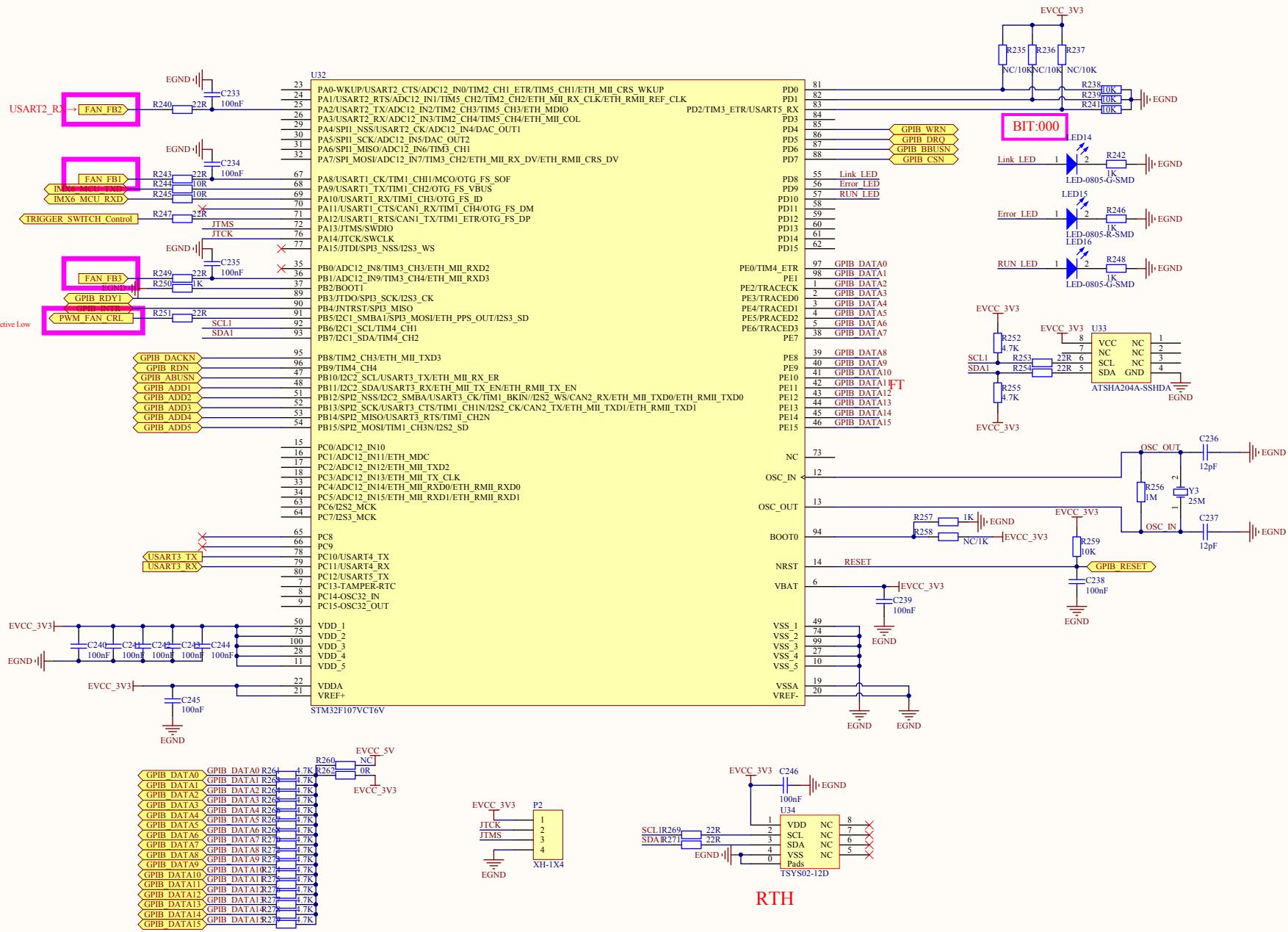




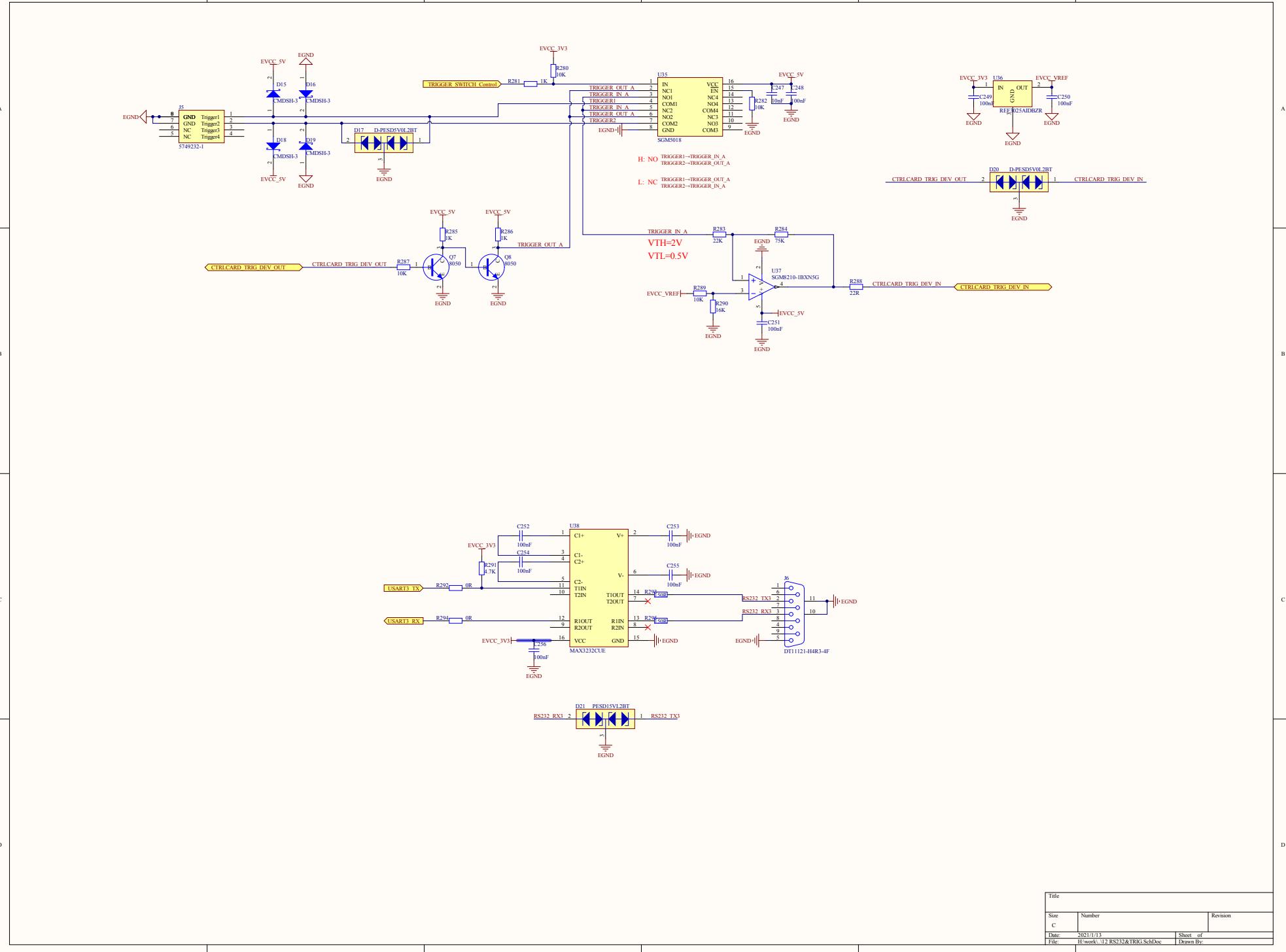


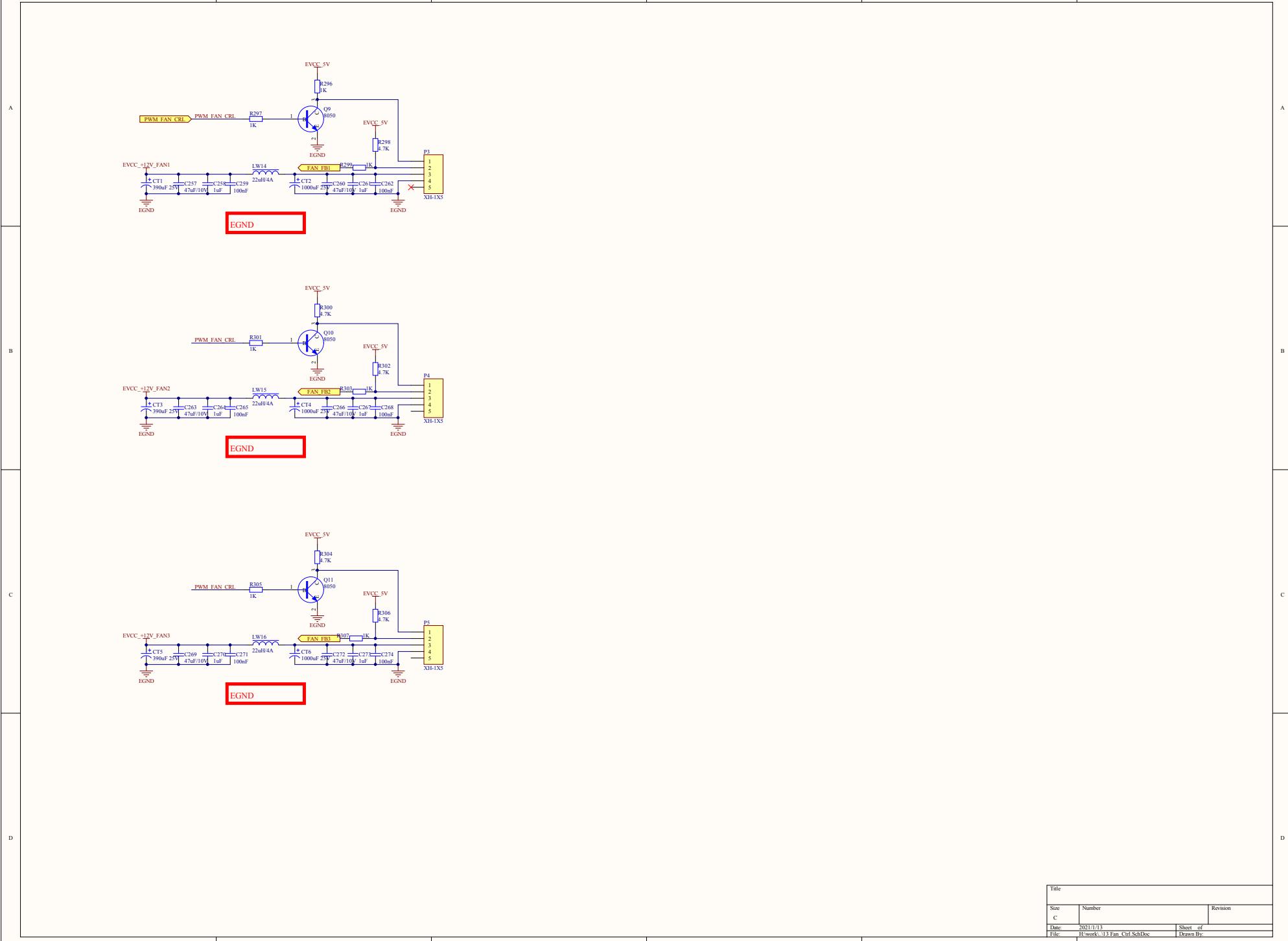


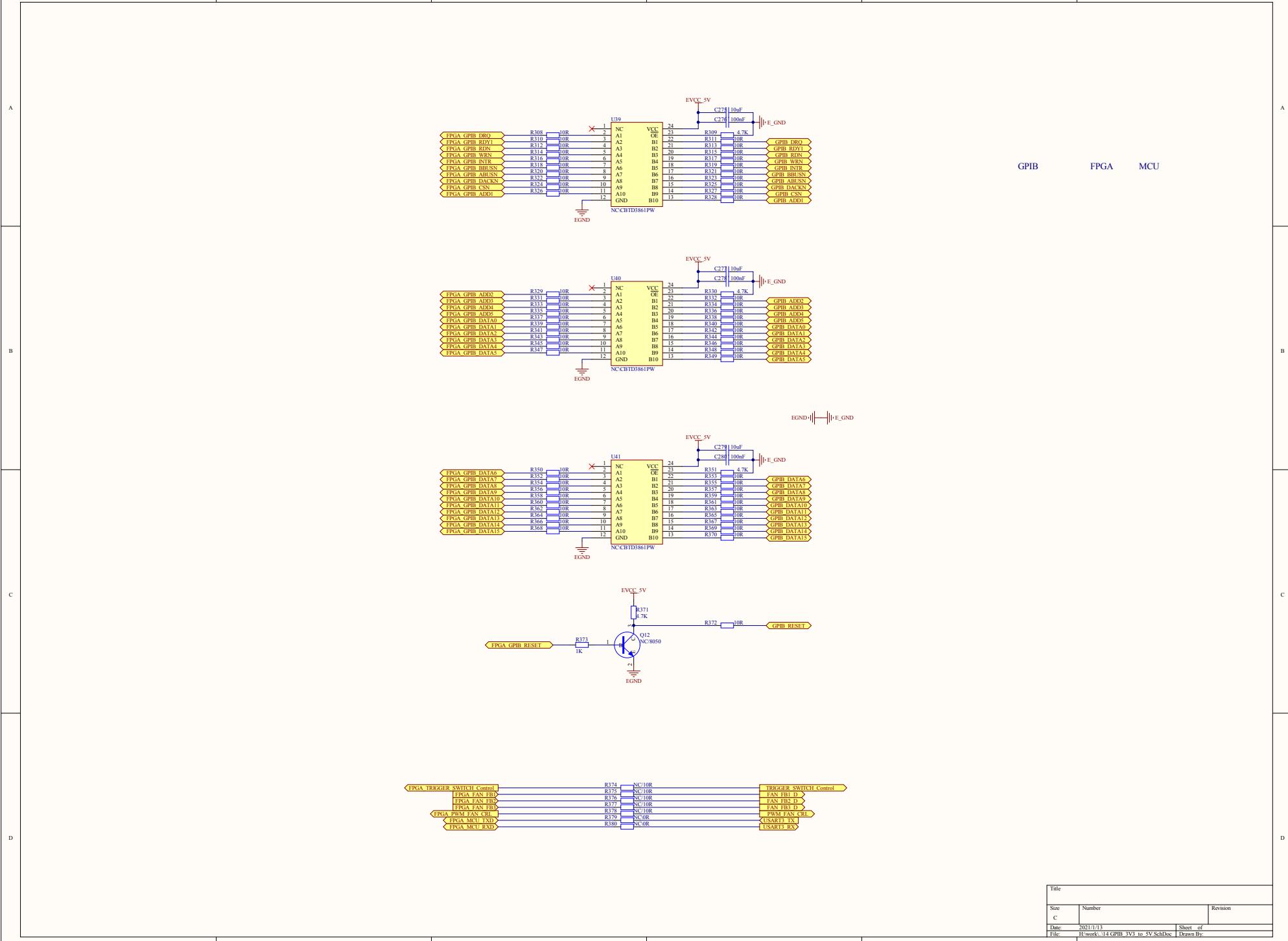
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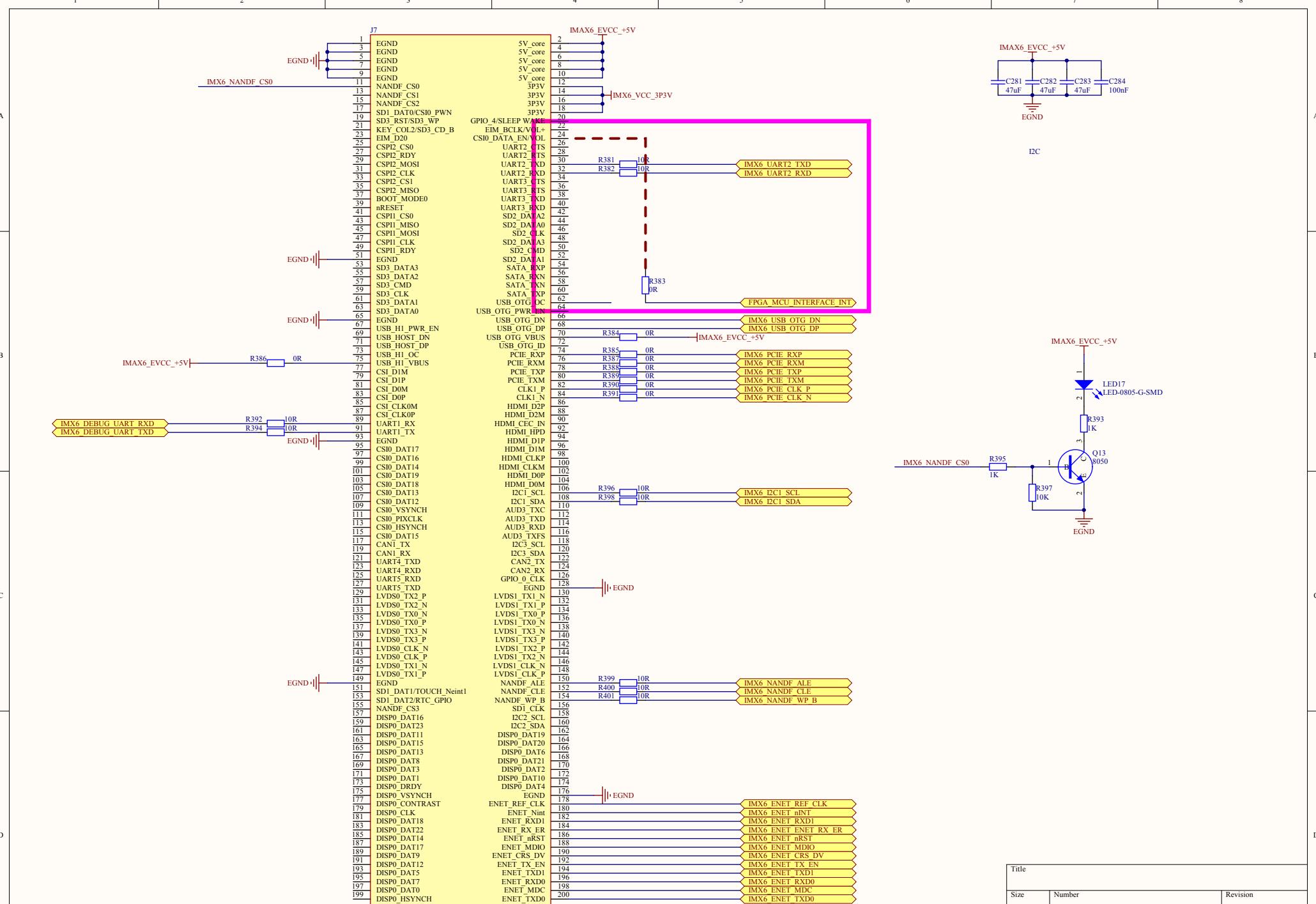


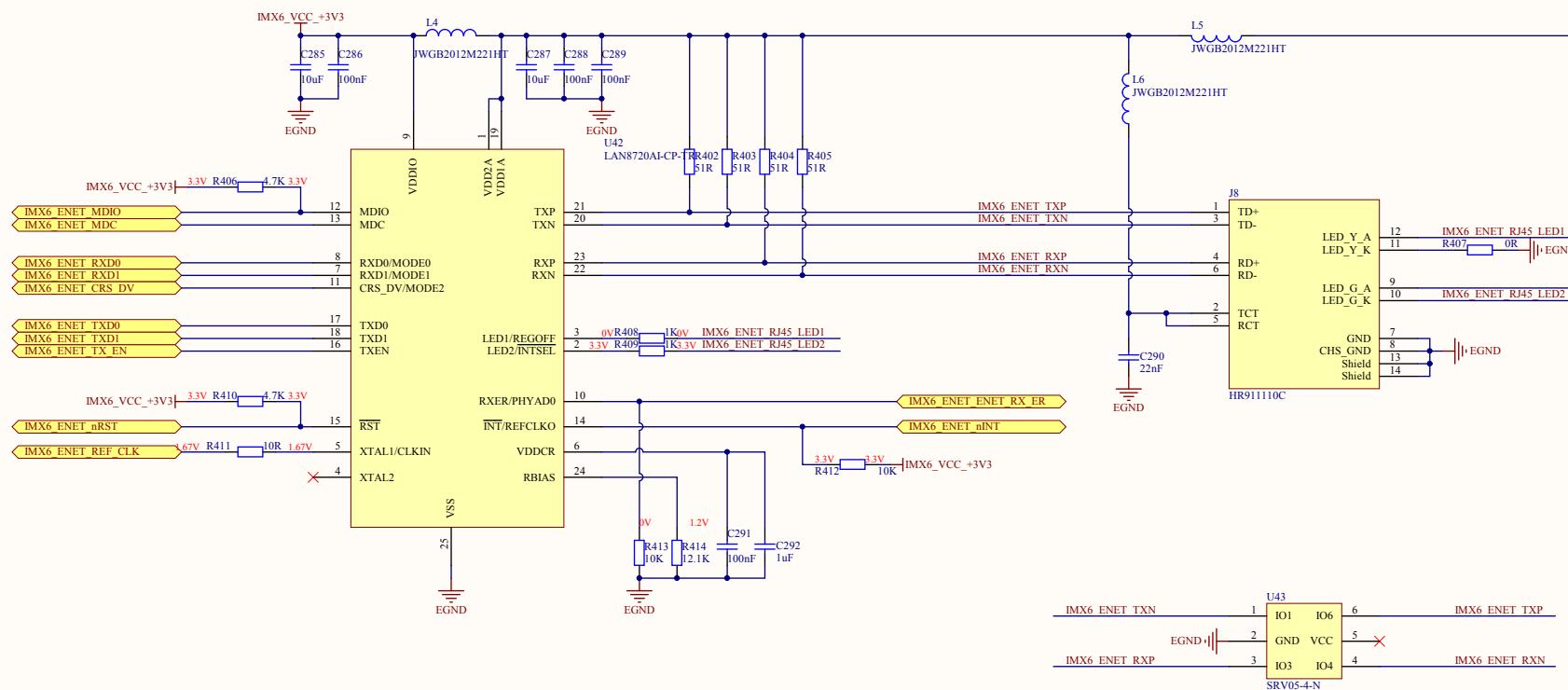
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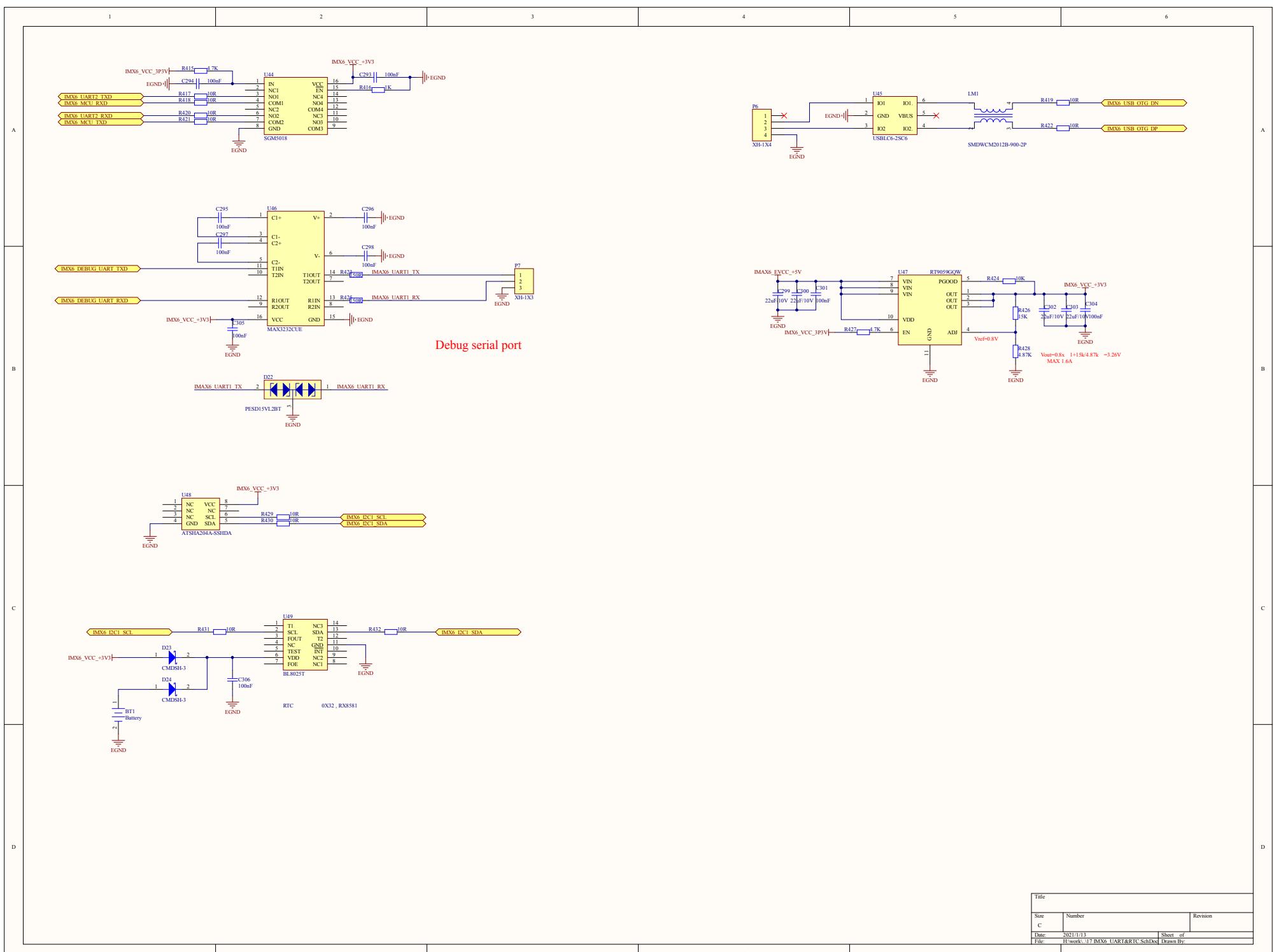






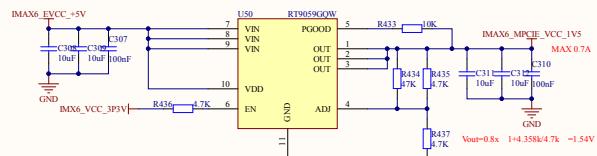


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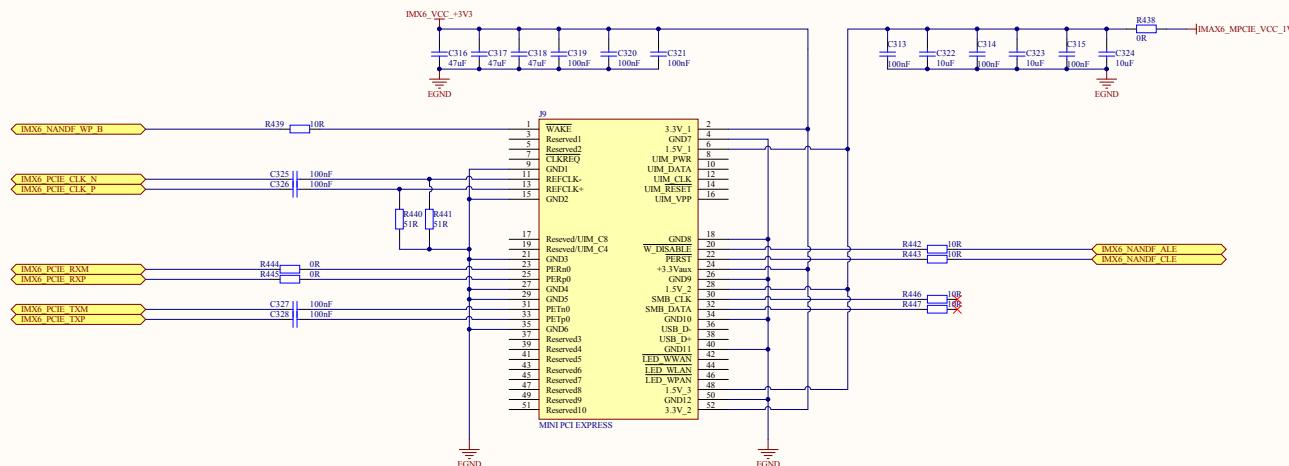
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